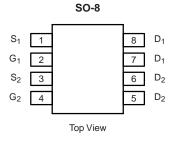


ELM14813AA-P-VB Datasheet Dual P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^{d, e}	Q _g (Typ.)			
- 30	0.021 at V _{GS} = - 10 V	- 8.0	15 nC			
- 30	0.028 at V _{GS} = - 4.5 V	- 7.0	13110			



FEATURES

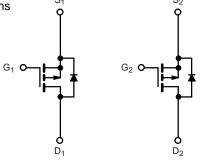
- · Halogen-free
- Trench Power MOSFET
- 100 % UIS Tested

Pb-free

RoHS

APPLICATIONS

- · Load Switches
 - Notebook PCs
 - Desktop PCs
 - Game Stations



P-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T	$_{A}$ = 25 °C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V_{GS}	± 20	v	
	T _C = 25 °C		- 9.5 ^e	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 8.0 ^e	
Continuous Diain Curient (1) = 130 °C)	T _A = 25 °C	l D	- 8.3 ^{a, b}	
	T _A = 70 °C		- 7.9 ^{a, b}	A
Pulsed Drain Current	I _{DM}	- 32 ^e	^	
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	l _s	- 2.0 ^{a, b}	
Avalanche Current	L = 0.1 mH	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	20	mJ
	T _C = 25 °C		5.0	
Manianum Danian Disain ation	T _C = 70 °C		3.2	w
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	VV
	T _A = 70 °C		1.6 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	R_{thJF}	20	25	7	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on $T_C = 25$ °C.
- e. Limited by package.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 31		\//90	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	ι _D = - 250 μΑ		4.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	1	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$		-1			
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5 µA		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
D : 0	В	V _{GS} = - 10 V, I _D = - 7.3 A		0.021		0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 6.2 A		0.028		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 9.1 A		23		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1350		pF	
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		215			
Reverse Transfer Capacitance	C _{rss}			185			
Total Cata Chausa		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -9.1 \text{ A}$		32	32 50		
Total Gate Charge	Q _g		15	25	200		
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -9.1 \text{ A}$		4		nC	
Gate-Drain Charge	Q_{gd}			7.5			
Gate Resistance	R_g	f = 1 MHz		5.8		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 15 \Omega$		8	15		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		45	70		
Fall Time	t _f	_		12	25		
Turn-On Delay Time	t _{d(on)}			42	70	ns	
Rise Time	ì,	V_{DD} = - 15 V, R_L = 15 Ω		35	60	1	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	70		
Fall Time	ì _f			16	30		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	۸	
Pulse Diode Forward Current	I _{SM}				- 32	Α	
Body Diode Voltage	V _{SD}	I _S = -2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	7 63		34	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 2 A d1/d+ 400 A/: T 05 00		22	40	nC	
Reverse Recovery Fall Time	t _a	$I_F = -2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		11			
Reverse Recovery Rise Time	t _b			23		ns	

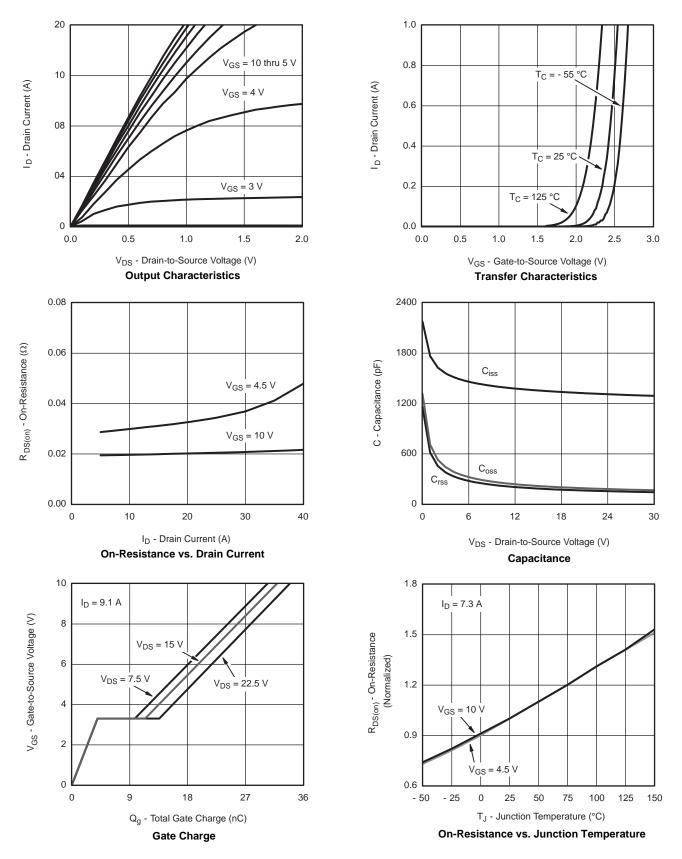
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

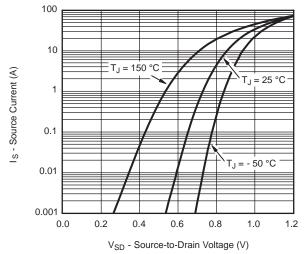
a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

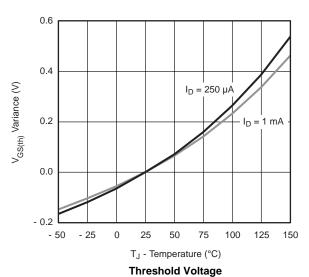






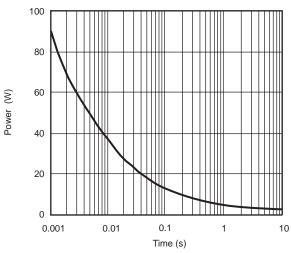


Source-Drain Diode Forward Voltage

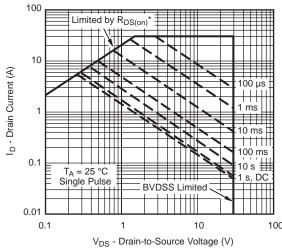


0.10 I_D = 7.3 A 0.08 $R_{DS(on)}$ - On-Resistance (Ω) 0.06 T_J = 125 °C 0.04 0.02 T_J = 25 °C 0.00 0 6 10

V_{GS} - Gate-to-Source Voltage (V) On-Resistance vs. Gate-to-Source Voltage



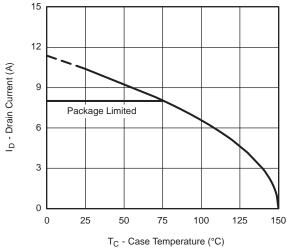
Single Pulse Power, Junction-to-Ambient



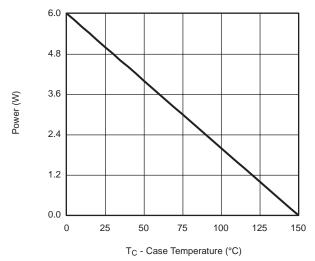
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

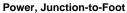
Safe Operating Area

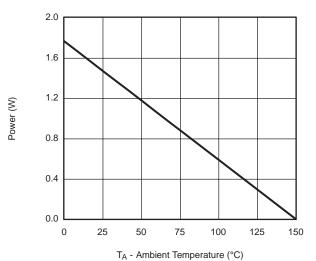








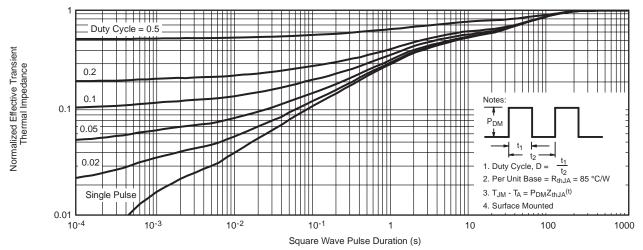




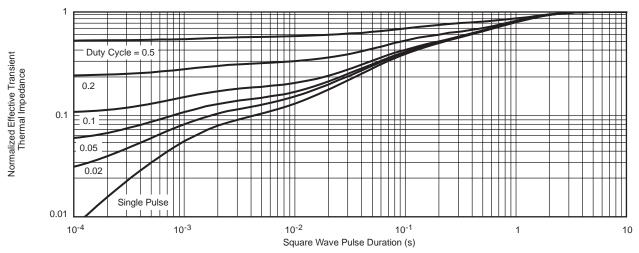
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package





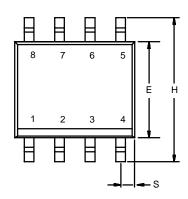
Normalized Thermal Transient Impedance, Junction-to-Ambient

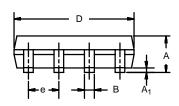


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







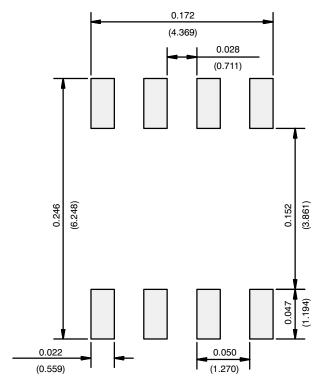
	MILLIM	MILLIMETERS INCHES				
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C 06527 Pay 1 11 Son 06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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